



YANGZHOU POSITIONING TECH.CO.,LTD

IRF50N06

N-Channel PowerTrench[®] MOSFET 60V, 50A, 15mΩ

General Description

This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low $r_{DS(ON)}$ and fast switching speed.

Applications

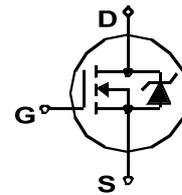
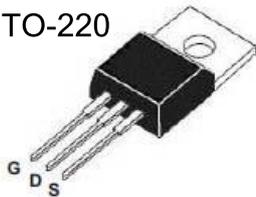
- DC/DC converters

Features

- $r_{DS(ON)} = 15m\Omega$, $V_{GS} = 10V$, $I_D = 30A$
- High performance trench technology for extremely low $r_{DS(ON)}$
- Low gate charge
- High power and current handling capability

PIN CONFIGURATION

TO-220



MOSFET Maximum Ratings $T_C = 25^\circ C$ unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DSS}	Drain to Source Voltage	60	V
V_{GS}	Gate to Source Voltage	± 20	V
I_D	Drain Current		
	Continuous ($T_C = 25^\circ C$, $V_{GS} = 10V$) (Note 1)	50	A
	Continuous ($T_C = 25^\circ C$, $V_{GS} = 4.5V$) (Note 1)	45	A
	Pulsed	Figure 4	A
E_{AS}	Single Pulse Avalanche Energy (Note 2)	53	mJ
P_D	Power dissipation	50	W
	Derate above $25^\circ C$	0.37	W/ $^\circ C$
T_J, T_{STG}	Operating and Storage Temperature	-55 to 175	$^\circ C$

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance Junction to Case TO-252	2.73	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance Junction to Ambient TO-252	100	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance Junction to Ambient TO-252, 1in ² copper pad area	52	$^\circ C/W$

Electrical Characteristics T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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Off Characteristics

V _{VDSS}	Drain to Source Breakdown Voltage	I _D = 250μA, V _{GS} = 0V	60	--		V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 24V V _{GS} = 0V	-	-	1	μA
I _{GSS}	Gate to Source Leakage Current	T _C = 150°C V _{GS} = ±20V	-	-	250	
			-	-	±100	nA

On Characteristics

V _{GS(TH)}	Gate to Source Threshold Voltage	V _{GS} = V _{DS} , I _D = 250μA	1.2	-	2.5	V
r _{DS(ON)}	Drain to Source On Resistance	I _D = 30A, V _{GS} = 10V -		-	0.015	Ω
		I _D = 35A, V _{GS} = 10V, T _J = 25°C	-	-	0.017	

Dynamic Characteristics

C _{ISS}	Input Capacitance	V _{DS} = 15V, V _{GS} = 0V, f = 1MHz	-	1260	-	pF
C _{OSS}	Output Capacitance		-	260	-	pF
C _{RSS}	Reverse Transfer Capacitance		-	150	-	pF
R _G	Gate Resistance	V _{GS} = 0.5V, f = 1MHz	-	2.3	-	Ω
Q _{g(TOT)}	Total Gate Charge at 10V	V _{GS} = 0V to 10V	-	23	31	nC
Q _{g(5)}	Total Gate Charge at 5V	V _{GS} = 0V to 5V	-	13	17	nC
Q _{g(TH)}	Threshold Gate Charge	V _{GS} = 0V to 1V	-	1.3	1.7	nC
Q _{gs}	Gate to Source Gate Charge	V _{DD} = 15V I _D = 30A I _g = 1.0mA	-	3.8	-	nC
Q _{gs2}	Gate Charge Threshold to Plateau		-	2.5	-	nC
Q _{gd}	Gate to Drain "Miller" Charge		-	5.0	-	nC

Switching Characteristics (V_{GS} = 10V)

t _{ON}	Turn-On Time	V _{DD} = 15V, I _D = 30A V _{GS} = 10V, R _{GS} = 10Ω	-	-	147	ns
t _{d(ON)}	Turn-On Delay Time		-	8	-	ns
t _r	Rise Time		-	91	-	ns
t _{d(OFF)}	Turn-Off Delay Time		-	38	-	ns
t _f	Fall Time		-	32	-	ns
t _{OFF}	Turn-Off Time		-	-	108	ns

Drain-Source Diode Characteristics

V _{SD}	Source to Drain Diode Voltage	I _{SD} = 30A	--		1.25V	
		I _{SD} = 15A	-	-	1.0	V
t _{rr}	Reverse Recovery Time	I _{SD} = 30A, dI _{SD} /dt = 100A/μs	-	-	27	ns
Q _{RR}	Reverse Recovered Charge	I _{SD} = 30A, dI _{SD} /dt = 100A/μs	-	-	14	nC

Notes:

- Package current limitation is 30A.
- Starting T_J = 25°C, L = 0.14mH, I_{AS} = 25A, V_{DD} = 27V, V_{GS} = 10V.